High Luminous Efficacy
Green LED Emitter

LZ1-00G100

Key Features

- High Luminous Efficacy Green LED
- Ultra-small foot print – 4.4mm x 4.4mm
- Surface mount ceramic package with integrated glass lens
- Very high Luminous Flux density
- New industry standard for Lumen Maintenance
- Autoclave complaint (JEDEC JESD22-A102-C)
- JEDEC Level 1 for Moisture Sensitivity Level
- Lead (Pb) free and RoHS compliant
- Reflow solderable (up to 6 cycles)
- Emitter available on Standard or Miniature MCPCB (optional)

Typical Applications

- Indoor and outdoor Architectural Lighting
- Display Backlighting
- Full Color Displays
- Projectors

Description

The LZ1-00G100 Green LED emitter provides 5W power in an extremely small package. With a 4.4mm x 4.4mm ultra-small footprint, this package provides exceptional luminous flux density. The patent-pending design has unparalleled thermal and optical performance and excellent UV resistance. The high quality materials used in the package are chosen to optimize light output and minimize stresses which results in monumental reliability and lumen maintenance. The robust product design thrives in outdoor applications with high ambient temperatures and high humidity.

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Part number options

Base part number

Part number	Description
LZ1-00G100-xxxx	LZ1 emitter
LZ1-10G100-xxxx	LZ1 emitter on Standard Star MCPCB
LZ1-30G100-xxxx	LZ1 emitter on Miniature round MCPCB

Bin kit option codes

G1, Green (525nm)			
Kit number suffix	**Min flux Bin**	**Color Bin Range**	**Description**
0000	N	G2 – G4	full distribution flux; full distribution wavelength
0G23	N	G2 – G3	full distribution flux; wavelength G2 and G3 bins

Notes:
1. Default bin kit option is -0000

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Luminous Flux Bins

Table 1:

Bin Code	Minimum Luminous Flux (Φ_V) @ I_F = 1000mA [1,2,3] (lm)	Maximum Luminous Flux (Φ_V) @ I_F = 1000mA [1,2,3] (lm)
N	145	182
P	182	228
Q	228	285

Notes for Table 1:
1. Luminous flux performance guaranteed within published operating conditions.
2. LED Engin maintains a tolerance of ± 10% on flux measurements.
3. Future products will have even higher levels of luminous flux performance. Contact LED Engin Sales for updated information.

Dominant Wavelength Bins

Table 2:

Bin Code	Minimum Dominant Wavelength (λ_D) @ I_F = 1000mA [1,2] (nm)	Maximum Dominant Wavelength (λ_D) @ I_F = 1000mA [1,2] (nm)
G2	520	525
G3	525	530
G4	530	535

Notes for Table 2:
1. Dominant wavelength is derived from the CIE 1931 Chromaticity Diagram and represents the perceived hue.
2. LED Engin maintains a tolerance of ± 1.0nm on dominant wavelength measurements.

Forward Voltage Bins

Table 3:

Bin Code	Minimum Forward Voltage (V_F) @ I_F = 1000mA [1] (V)	Maximum Forward Voltage (V_F) @ I_F = 1000mA [1] (V)
J	3.20	4.20

Notes for Table 3:
1. LED Engin maintains a tolerance of ± 0.04V for forward voltage measurements.

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Absolute Maximum Ratings

Table 4:

Parameter	Symbol	Value	Unit
DC Forward Current at T_{jmax}=135°C [1]	I_F	1200	mA
DC Forward Current at T_{jmax}=150°C [1]	I_F	1000	mA
Peak Pulsed Forward Current [2]	I_{FP}	2000	mA
Reverse Voltage	V_R	See Note 3	V
Storage Temperature	T_{stg}	-40 ~ +150	°C
Junction Temperature	T_J	150	°C
Soldering Temperature [4]	T_{sol}	260	°C
Allowable Reflow Cycles		6	
Autoclave Conditions [5]		121°C at 2 ATM, 100% RH for 168 hours	
ESD Sensitivity [6]		> 1,000 V HBM Class 1C JESD22-A114-D	

Notes for Table 4:
1. Maximum DC forward current is determined by the overall thermal resistance and ambient temperature. Follow the curves in Figure 11 for current derating.
2: Pulse forward current conditions: Pulse Width ≤ 10msec and Duty cycle ≤ 10%.
3. LEDs are not designed to be reverse biased.
4. Solder conditions per JEDEC 020c. See Reflow Soldering Profile Figure 3.
5. Autoclave Conditions per JEDEC JESD22-A102-C.
6. LED Engin recommends taking reasonable precautions towards possible ESD damages and handling the LZ1-00G100 in an electrostatic protected area (EPA). An EPA may be adequately protected by ESD controls as outlined in ANSI/ESD S6.1.

Optical Characteristics @ T_C = 25°C

Table 5:

Parameter	Symbol	Typical	Unit
Luminous Flux (@ I_F = 1000mA)	Φ_V	200	lm
Dominant Wavelength (@ I_F = 700mA)	λ_D	523	nm
Viewing Angle [1]	$2\Theta_{1/2}$	80	Degrees
Total Included Angle [2]	$\Theta_{0.9}$	90	Degrees

Notes for Table 5:
1. Viewing Angle is the off axis angle from emitter centerline where the luminous intensity is ½ of the peak value.
2. Total Included Angle is the total angle that includes 90% of the total luminous flux.

Electrical Characteristics @ T_C = 25°C

Table 6:

Parameter	Symbol	Typical	Unit
Forward Voltage (@ I_F = 1000mA)	V_F	3.75	V
Forward Voltage (@ I_F = 1200mA)	V_F	3.85	V
Temperature Coefficient of Forward Voltage	$\Delta V_F/\Delta T_J$	-4.0	mV/°C
Thermal Resistance (Junction to Case)	$R\Theta_{J-C}$	10.5	°C/W

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IPC/JEDEC Moisture Sensitivity Level

Table 7 - IPC/JEDEC J-STD-20D.1 MSL Classification:

			Soak Requirements			
	Floor Life		Standard		Accelerated	
Level	Time	Conditions	Time (hrs)	Conditions	Time (hrs)	Conditions
1	Unlimited	≤ 30°C/ 85% RH	168 +5/-0	85°C/ 85% RH	n/a	n/a

Notes for Table 7:
1. The standard soak time includes a default value of 24 hours for semiconductor manufacturer's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

Average Lumen Maintenance Projections

Lumen maintenance generally describes the ability of a lamp to retain its output over time. The useful lifetime for solid state lighting devices (Power LEDs) is also defined as Lumen Maintenance, with the percentage of the original light output remaining at a defined time period.

Based on long-term WHTOL testing, LED Engin projects that the LZ Series will deliver, on average, 70% Lumen Maintenance at 65,000 hours of operation at a forward current of
1000 mA. This projection is based on constant current operation with junction temperature maintained at or below 125°C.

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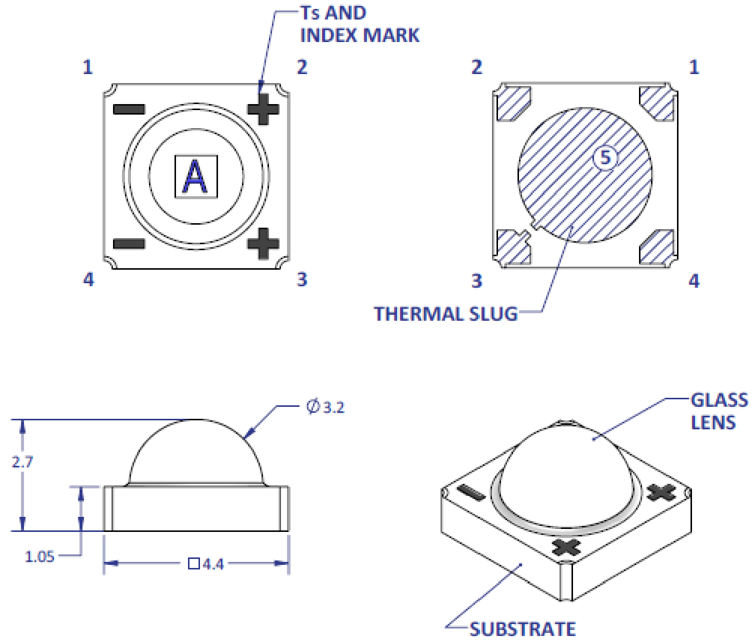
Mechanical Dimensions (mm)



Pin Out	
Pad	Function
1	Cathode
2	Anode
3	Anode
4	Cathode
5 [2]	Thermal

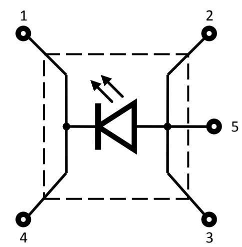


Figure 1: Package outline drawing.

Notes for Figure 1:

1. Unless otherwise noted, the tolerance = ± 0.20 mm.
2. Thermal contact, Pad 5, is electrically connected to the Anode, Pads 2 and 3. Do not connect any pad to the thermal contact, Pad # 5. When mounting the LZ1-00G100 onto a MCPCB, by default its dielectric layer provides for the necessary electrical insulation in between all contact pads. LED Engin offers LZ1-10G100 and LZ1-30G100 MCPCB options which provide for electrical insulation between all contact pads. Please refer to Application Note MCPCB Option 1 and Option 3, or contact a LED Engin sales representative for more information.

Recommended Solder Pad Layout (mm)

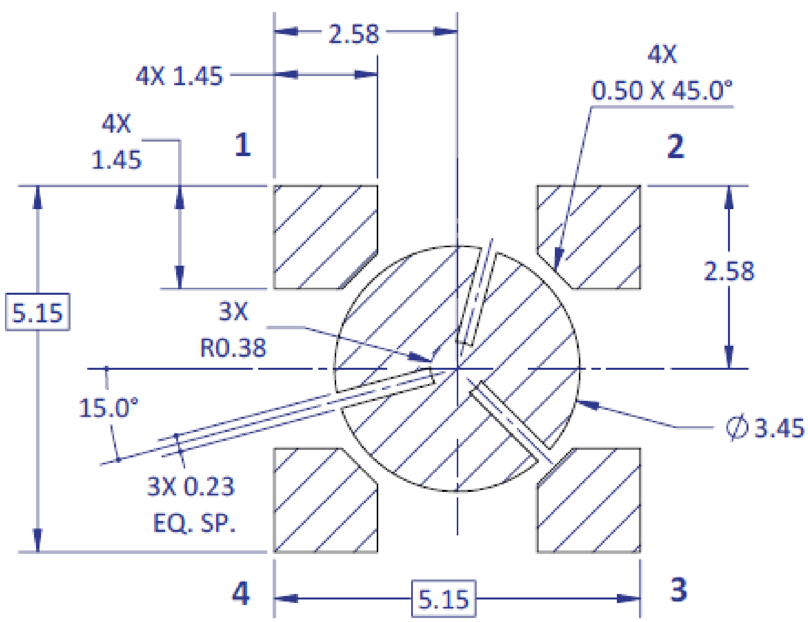


Figure 2: Recommended solder mask opening (hatched area) for anode, cathode, and thermal pad.

Note for Figure 2:

1. Unless otherwise noted, the tolerance = ± 0.20 mm.

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Recommended Solder Mask Layout (mm)

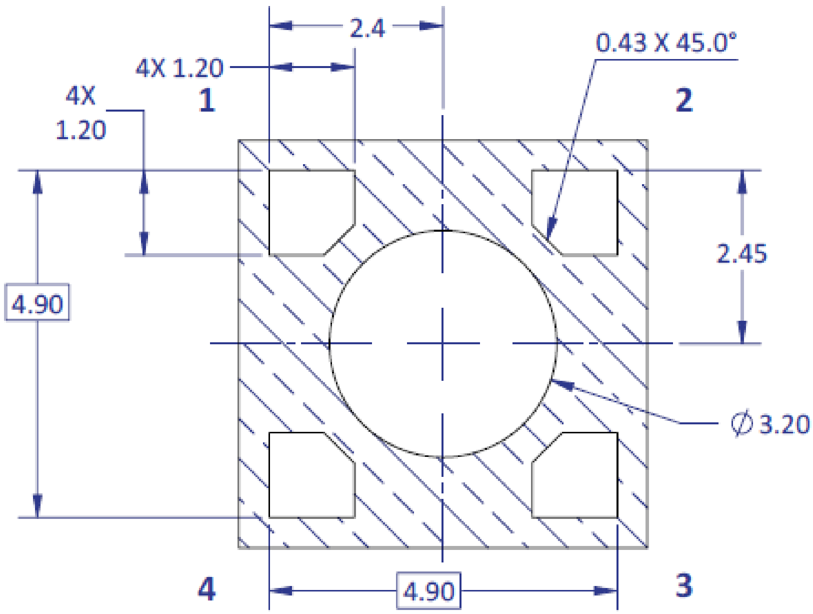

Figure 2b: Recommended solder mask opening for anode, cathode, and thermal pad

Note for Figure 2b:
1. Unless otherwise noted, the tolerance = ± 0.20 mm.

Recommended 8mil Stencil Apertures Layout (mm)

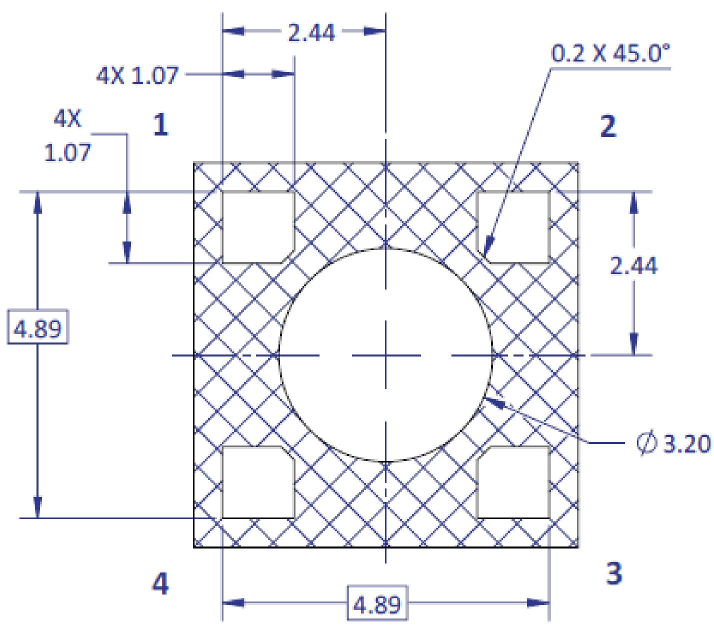

Figure 2c: Recommended 8mil stencil apertures layout for anode, cathode, and thermal pad

Note for Figure 2c:
1. Unless otherwise noted, the tolerance = ± 0.20 mm.

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Reflow Soldering Profile

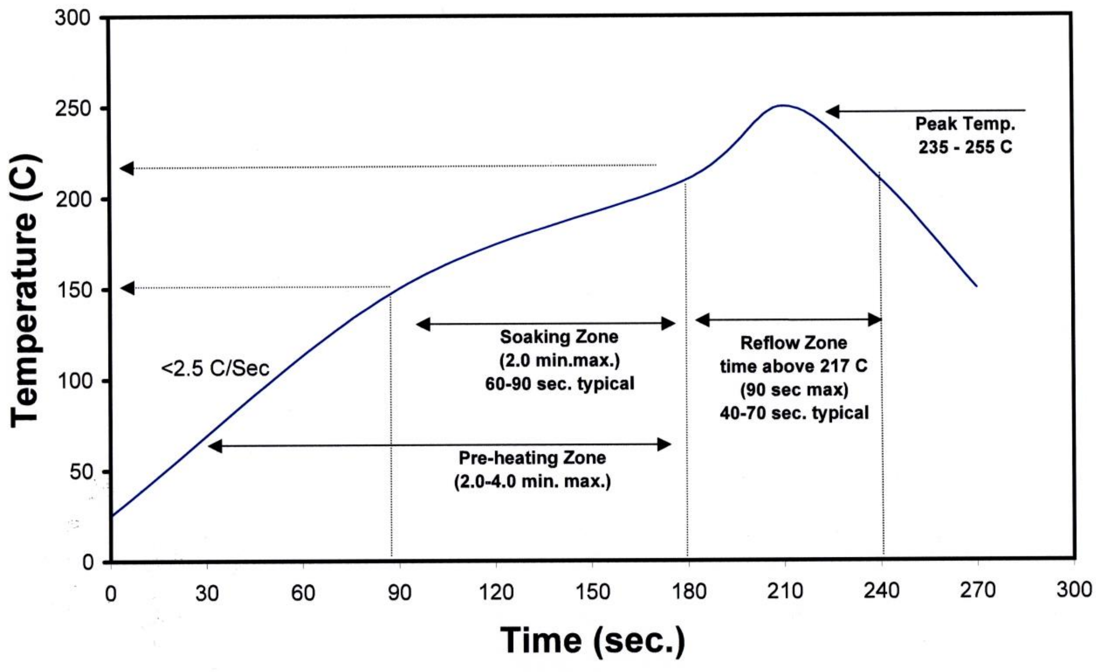

Figure 3: Reflow soldering profile for lead free soldering.

Typical Radiation Pattern

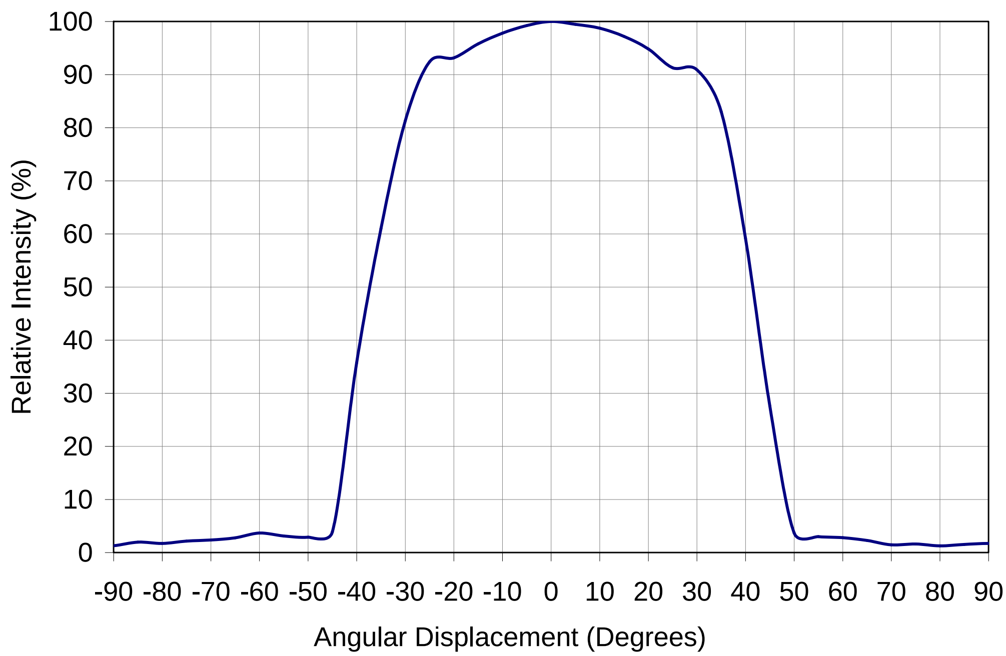

Figure 4: Typical representative spatial radiation pattern @ T_C = 25°C.

Typical Relative Spectral Power Distribution

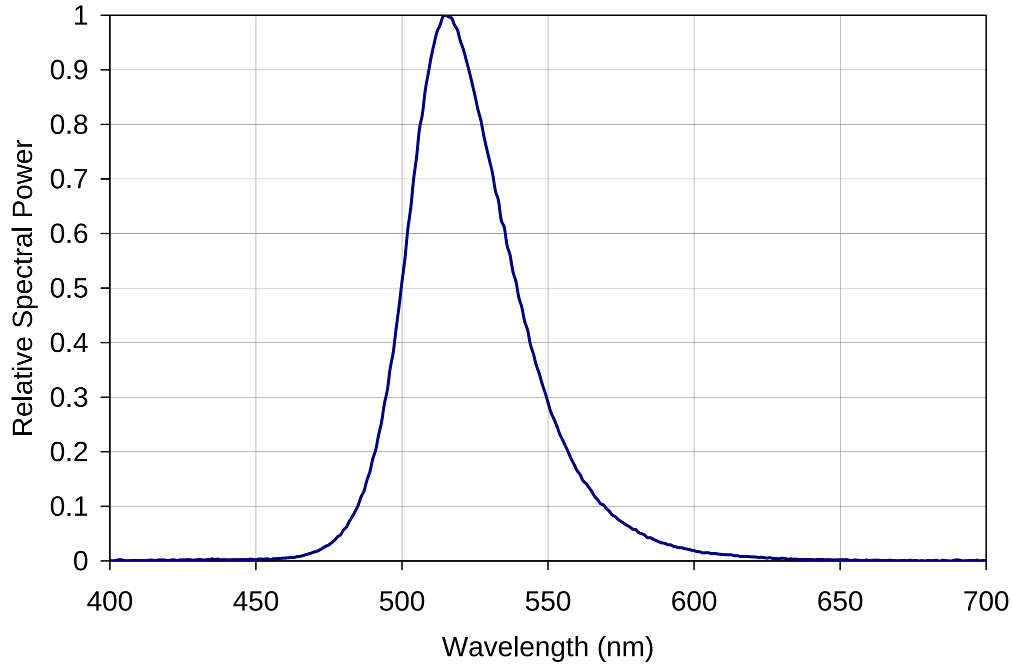

Figure 5: Relative spectral power vs. wavelength @ I_F = 350mA and T_C = 25°C.

Typical Relative Dominant Wavelength Shift

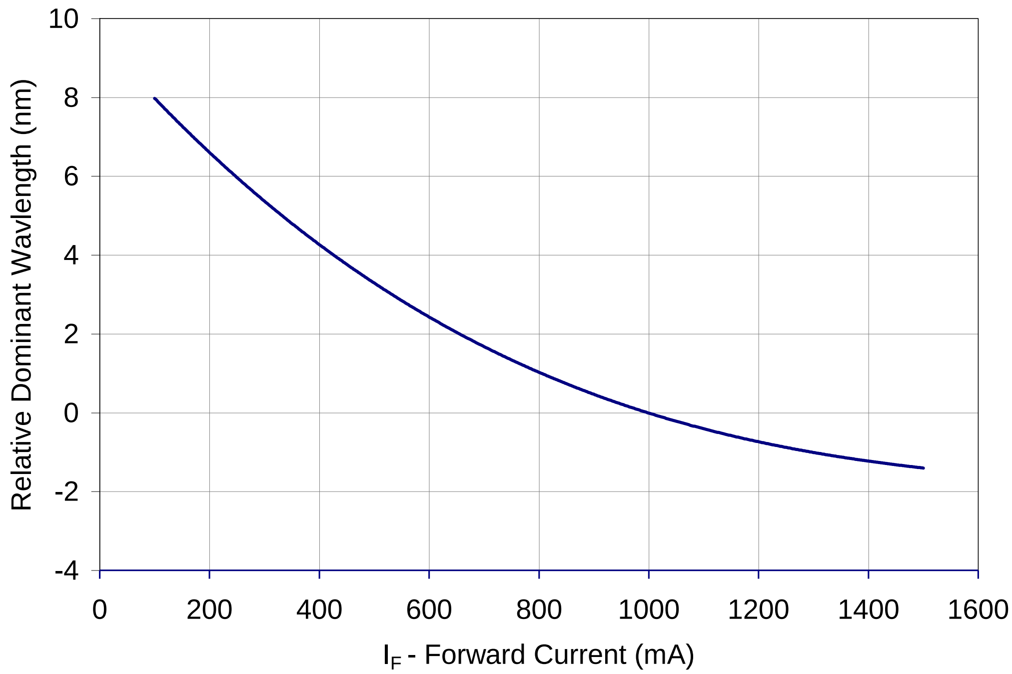

Figure 6: Typical dominant wavelength shift vs. forward current @ T_C = 25°C.

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Typical Relative Dominant Wavelength Shift over Temperature

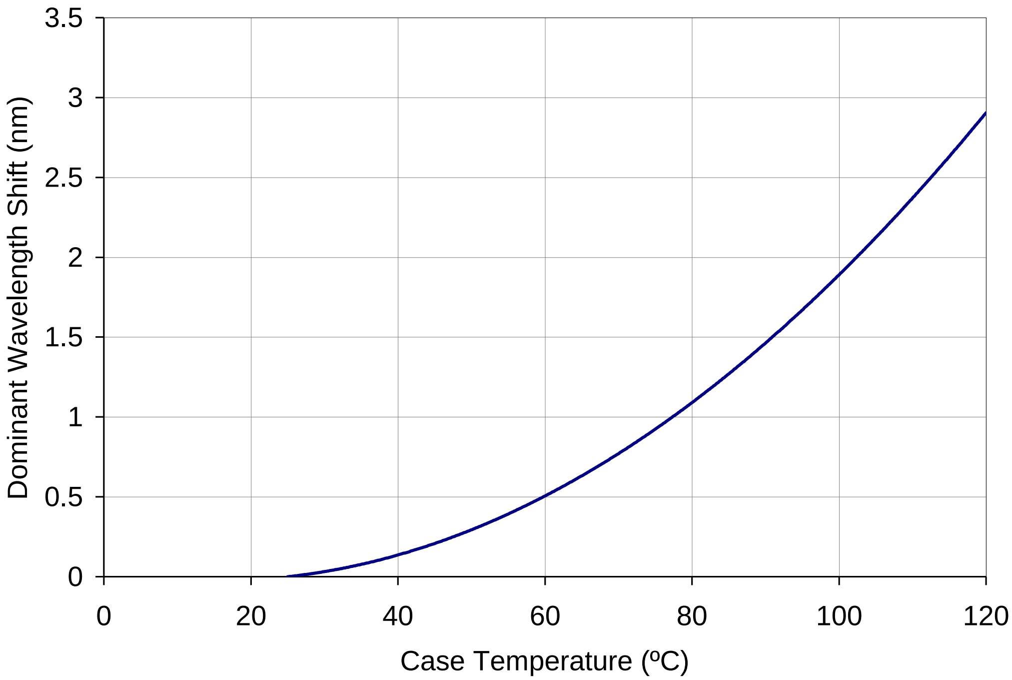

Figure 7: Typical dominant wavelength shift vs. case temperature.

Typical Relative Light Output

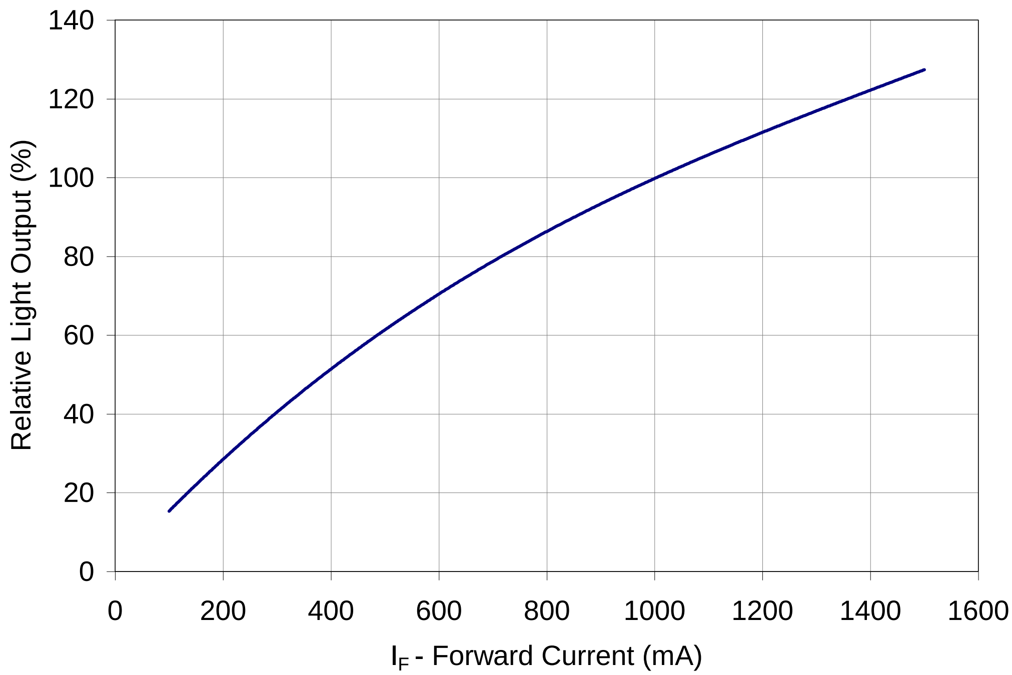

Figure 8: Typical relative light output vs. forward current @ T_C = 25°C.

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Typical Relative Light Output over Temperature

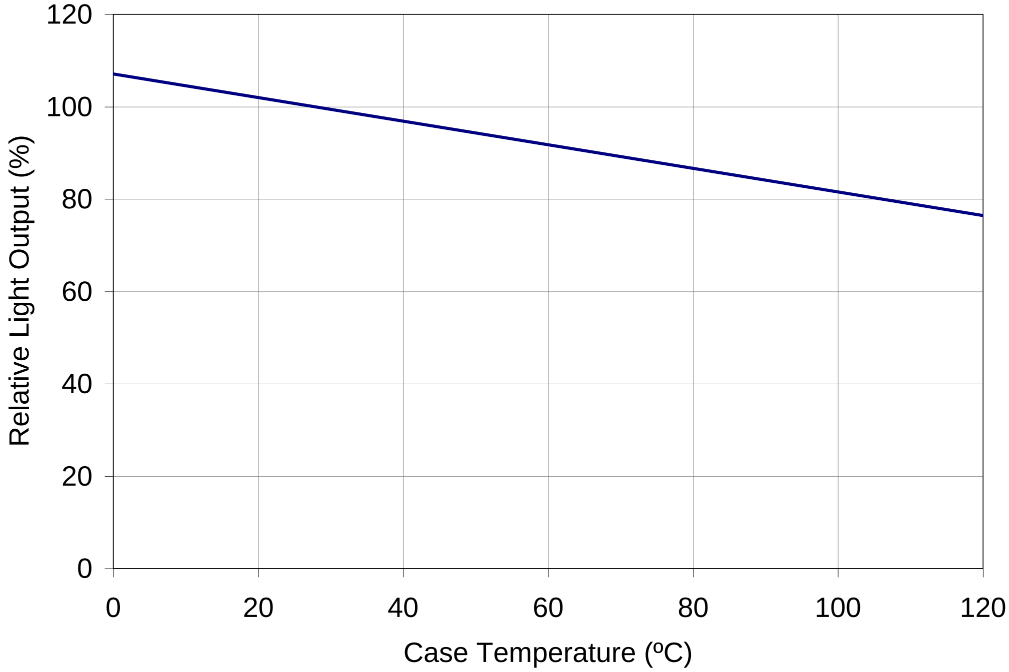

Figure 9: Typical relative light output vs. case temperature.

Typical Forward Current Characteristics

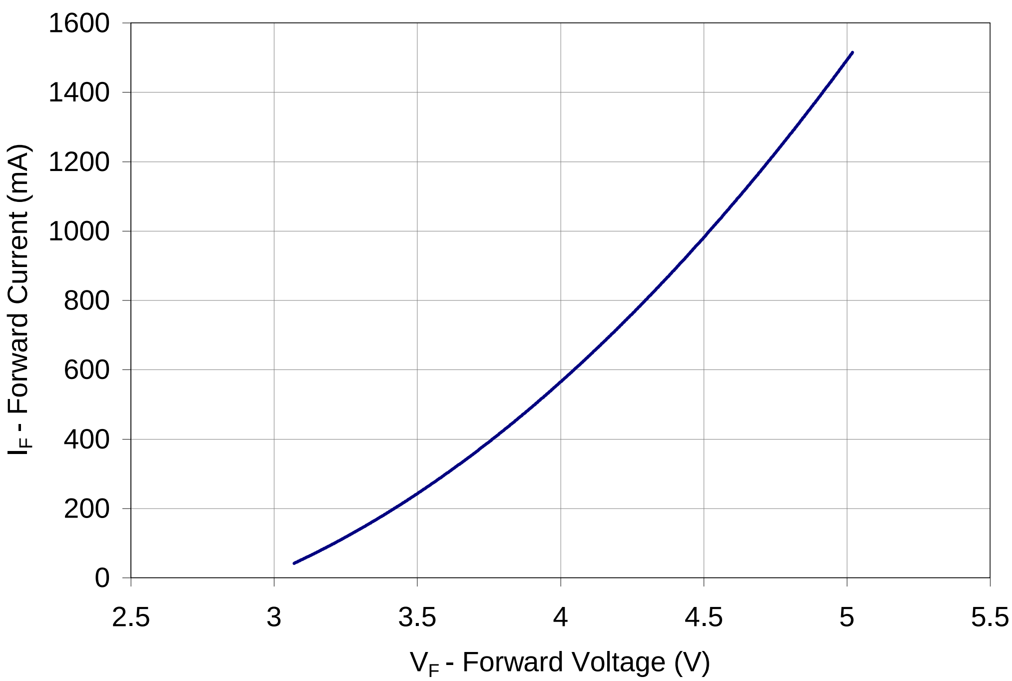

Figure 10: Typical forward current vs. forward voltage @ T_C = 25°C.

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Current Derating

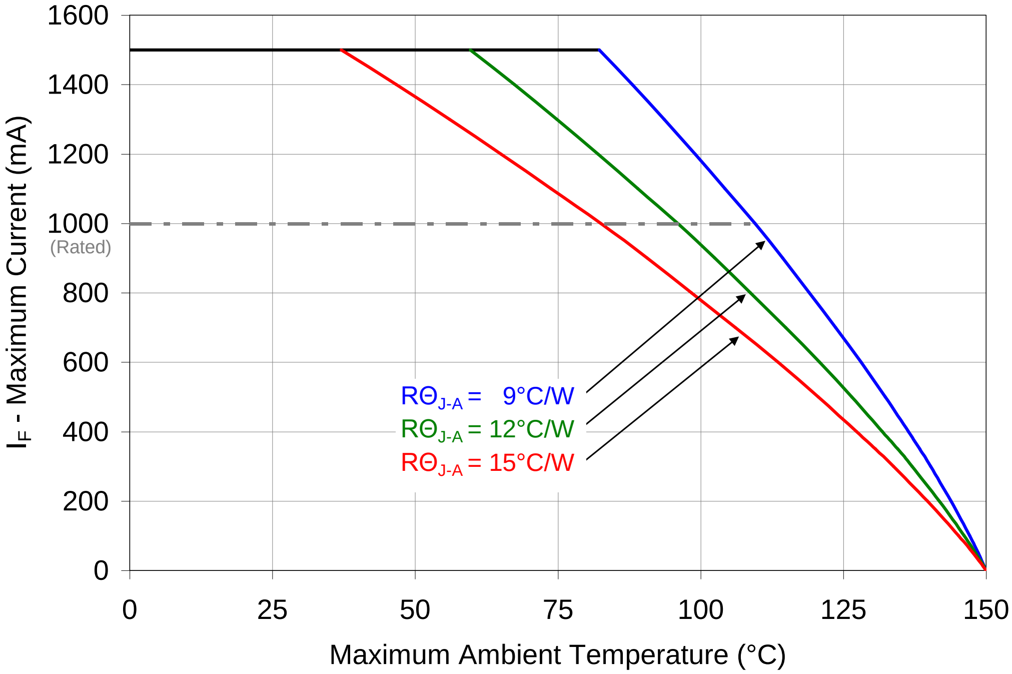

Figure 11: Maximum forward current vs. ambient temperature based on $T_{J(MAX)}$ = 150°C.

Notes for Figure 11:

1. $R\Theta_{J\text{-}C}$ [Junction to Case Thermal Resistance] for the LZ1-00G100 is typically 9°C/W-11°C/W.
2. $R\Theta_{J\text{-}A}$ [Junction to Ambient Thermal Resistance] = $R\Theta_{J\text{-}C}$ + $R\Theta_{C\text{-}A}$ [Case to Ambient Thermal Resistance].

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Emitter Tape and Reel Specifications (mm)

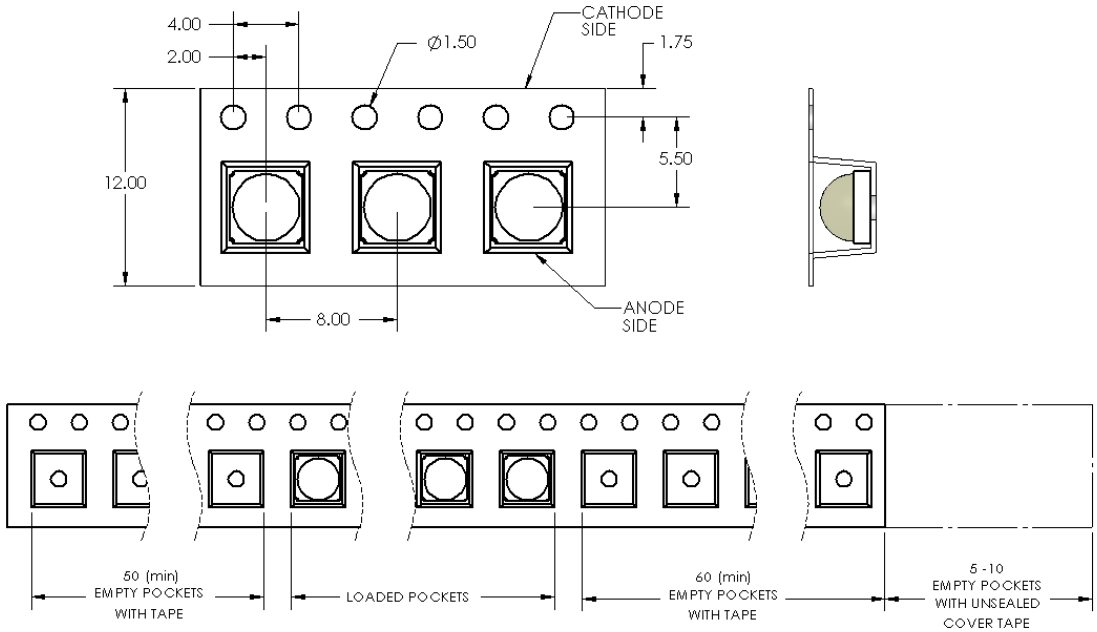

Figure 12: Emitter carrier tape specifications (mm).

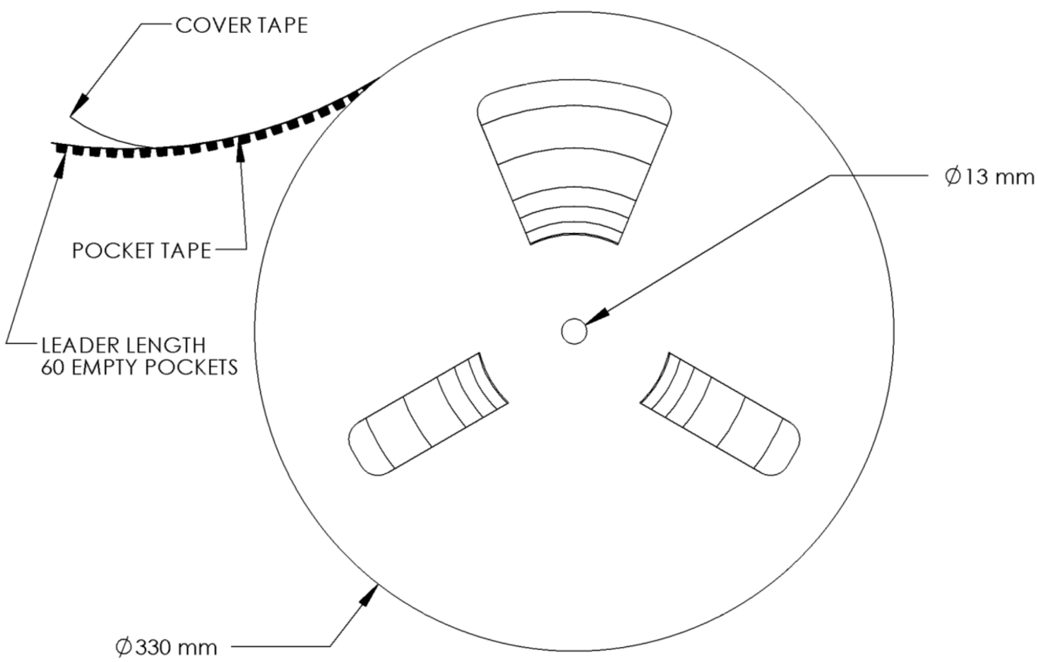

Figure 13: Emitter reel specifications (mm).

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LZ1 MCPCB Family

Part number	Type of MCPCB	Diameter (mm)	Emitter + MCPCB Thermal Resistance ($^oC/W$)	Typical V_f (V)	Typical I_f (mA)
LZ1-1xxxxx	1-channel Star	19.9	10.5 + 1.5 = 12.0	4.5	1000
LZ1-3xxxxx	1-channel Mini	11.5	10.5 + 2.0 = 12.5	4.5	1000

Mechanical Mounting of MCPCB

- MCPCB bending should be avoided as it will cause mechanical stress on the emitter, which could lead to substrate cracking and subsequently LED dies cracking.
- To avoid MCPCB bending:
  - Special attention needs to be paid to the flatness of the heat sink surface and the torque on the screws.
  - Care must be taken when securing the board to the heat sink. This can be done by tightening three M3 screws (or #4-40) in steps and not all the way through at once. Using fewer than three screws will increase the likelihood of board bending.
  - It is recommended to always use plastics washers in combinations with the three screws.
  - If non-taped holes are used with self-tapping screws, it is advised to back out the screws slightly after tightening (with controlled torque) and then re-tighten the screws again.

Thermal interface material

- To properly transfer heat from LED emitter to heat sink, a thermally conductive material is required when mounting the MCPCB on to the heat sink.
- There are several varieties of such material: thermal paste, thermal pads, phase change materials and thermal epoxies. An example of such material is Electrolube EHTC.
- It is critical to verify the material's thermal resistance to be sufficient for the selected emitter and its operating conditions.

Wire soldering

- To ease soldering wire to MCPCB process, it is advised to preheat the MCPCB on a hot plate of 125-150^{o}C. Subsequently, apply the solder and additional heat from the solder iron will initiate a good solder reflow. It is recommended to use a solder iron of more than 60W.
- It is advised to use lead-free, no-clean solder. For example: SN-96.5 AG-3.0 CU 0.5 #58/275 from Kester (pn: 24-7068-7601)

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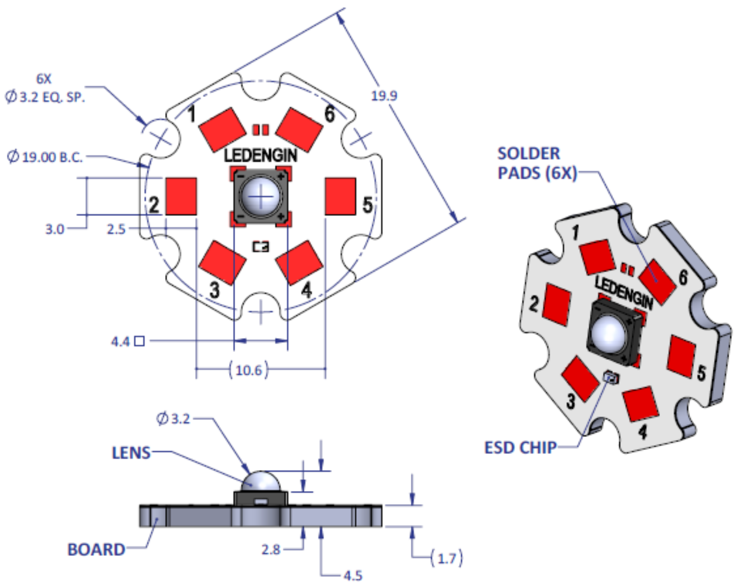
LZ1-1xxxxx

1 channel, Standard Star MCPCB (1x1) Dimensions (mm)



Notes:

- Unless otherwise noted, the tolerance = ± 0.2 mm.
- Slots in MCPCB are for M3 or #4-40 mounting screws.
- LED Engin recommends plastic washers to electrically insulate screws from solder pads and electrical traces.
- Electrical connection pads on MCPCB are labeled “+” for Anode and “-” for Cathode.
- LED Engin recommends using thermal interface material when attaching the MCPCB to a heat sink.
- The thermal resistance of the MCPCB is: RΘC-B 1.5°C/W

Components used

MCPCB:	HT04503	(Bergquist)
ESD/TVS Diode:	BZT52C5V1LP-7	(Diodes, Inc., for 1 LED die)
	VBUS05L1-DD1	(Vishay Semiconductors, for 1 LED die)

Pad layout			
Ch.	**MCPCB Pad**	**String/die**	**Function**
1	1,2,3	1/A	Cathode -
	4,5,6		Anode +

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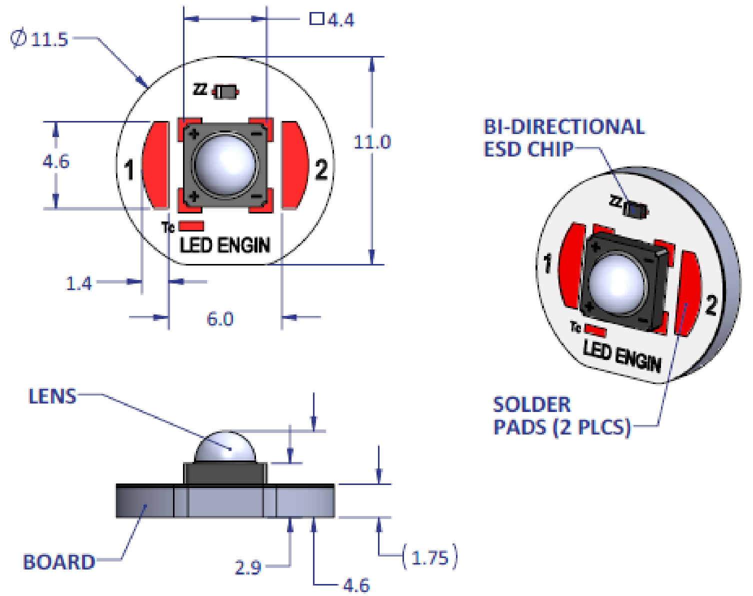
LZ1-3xxxxx

1 channel, Mini Round MCPCB (1x1) Dimensions (mm)



Notes:

- Unless otherwise noted, the tolerance = ± 0.20 mm.
- Electrical connection pads on MCPCB are labeled "+" for Anode and "-" for Cathode.
- LED Engin recommends using thermal interface material when attaching the MCPCB to a heat sink.
- The thermal resistance of the MCPCB is: RΘC-B 2.0°C/W

Components used

MCPCB:	HT04503	(Bergquist)
ESD/TVS Diode:	BZT52C5V1LP-7	(Diodes, Inc., for 1 LED die)
	VBUS05L1-DD1	(Vishay Semiconductors, for 1 LED die)

Pad layout			
Ch.	**MCPCB Pad**	**String/die**	**Function**
1	1	1/A	Anode +
	2		Cathode -

Company Information

LED Engin, Inc., based in California's Silicon Valley, specializes in ultra-bright, ultra compact solid state lighting solutions allowing lighting designers & engineers the freedom to create uncompromised yet energy efficient lighting experiences. The LuxiGen™ Platform — an emitter and lens combination or integrated module solution, delivers superior flexibility in light output, ranging from 3W to 90W, a wide spectrum of available colors, including whites, multi-color and UV, and the ability to deliver upwards of 5,000 high quality lumens to a target. The small size combined with powerful output allows for a previously unobtainable freedom of design wherever high-flux density, directional light is required. LED Engin's packaging technologies lead the industry with products that feature lowest thermal resistance, highest flux density and consummate reliability, enabling compact and efficient solid state lighting solutions.

LED Engin is committed to providing products that conserve natural resources and reduce greenhouse emissions.

LED Engin reserves the right to make changes to improve performance without notice.

Please contact sales@ledengin.com or (408) 922-7200 for more information.

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